« UNIBOND™ » WAFERS

Quality : PRIME	Diameter : 200mm
Commercial Part xxxx-xxx-01	
Product description : 5000/10000Å +/-200Å - base HR	

Top silicon layer

Parameters	Measurement equipment /conditions	Min	Target	Max	Unit
Metrology edge exclusion	All parameters			5	**mm**
SOI mean thickness +/- 3sigma	(2)	480	500	520	**nm**
Conductivity type	P type				
Dopant	Boron				
Resistivity	SEMI M1 (1)	8.5		11.5	**Ohmcm**
Crystal orientation	SEMI M1 (1)	-0.5	(100)	+0.5	**deg**
Crystal Growth Method	CZ cop free				
Light Point Defects (LPD)	SP1>0.2µm threshold (2)			200	**Count**
Area Count (LAD)	SP1>0.8µm threshold (2)			30	**Count**
Bonding voids	Visual inspection > 0.5 mm diameter (2)			none	**Count**
Surface defects (visual)	Edge chips, scratch, slip, stain (2)			none	**Count**
HF Defects	(2)			1	**DEF/cm2**
surface contamination_Fe	VPD-ICPMS (2)			5	**E10 at/cm²**
surface contamination_Cu	VPD-ICPMS (2)			5	**E10 at/cm²**
surface contamination_Cr	VPD-ICPMS (2)			5	**E10 at/cm²**
surface contamination_Ni	VPD-ICPMS (2)			5	**E10 at/cm²**
surface metal contamination_Zn	VPD-ICPMS (2)			5	**E10 at/cm²**
surface	VPD-ICPMS (2)			5	**E10**

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contamination_Na					**at/cm²**
surface contamination_Ca	VPD-ICPMS (2)			5	**E10 at/cm²**
surface contamination_Al	VPD-ICPMS (2)			5	**E10 at/cm²**
Surface roughness	Mirror polished				

Buried oxide

Parameters	**Measurement equipment /conditions**	**Min**	**Target**	**Max**	**Unit**
Metrology edge exclusion	All parameters			5	**mm**
Mean thickness	(2)	900	1000	1100	**nm**
Within wafer thickness standard deviation	(2)			4	**nm**

Mechanical parameters

Parameters	**Measurement equipment /conditions**	**Min**	**Target**	**Max**	**Unit**
Metrology edge exclusion	All parameters			5	**mm**
Thickness	SEMI M1 (1)	710	725	740	**µm**
Diameter	SEMI M1 (1)	199.8	200	200.2	**mm**
TTV	(1)			5	**µm**
SFQR max	Site size : 25 x 25 mm (1)			0.15	**µm**
Warp	(2)			60	**µm**

Handle wafer

Parameters	**Measurement equipment /conditions**	**Min**	**Target**	**Max**	**Unit**

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Metrology edge exclusion	All parameters			5	**mm**
Notch orientation axis	SEMI M1 (1)	-1	<110>	+1	**deg**
Conductivity type	N/A				
Resistivity	SEMI M1 (1)	750	1000		**Ohmcm**
Crystal orientation	SEMI M1 (1)	-0.5	(100)	+0.5	**deg**
Crystal Growth Method	Standard CZ				
Carbon Content	ASTM F1391 (1)			0.3	**ppma**
Oxygen Content	ASTM F1188 (1) - max : N/S	13			**new ppma**
Backside surface	WSB / Oxidized				
Lasermark	backside				

(1) Data based on bulk silicon measurements(2) Data based on Soitec internal measurements procedure

Packing & Labelling

Packaging boxes are Ultrapak boxes. Maximum wafer number per box is 25. Double vacuum seal protects each box. Transport packaging are reinforced by cardboard containers, in which the boxes are held in place and protected by performed shells. Two labels are affixed, one on the inner Ultrapak box and the other one on the outer aluminum bag. Labels contain commercial part reference, quantity, production date, lot number and additional product information.

General Information

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